

SECURE, SMART, STANDARDIZED, AND CONNECTED IOT: POWERFUL NXP EDGE PROCESSING WITH WI-FI 6 OR WI-FI 6E



MADE IN THE USA

Featuring **NXP i.MX 8M Mini** with optional **NXP** and **Infineon** based **Wi-Fi 6** or **Wi-Fi 6E** with **Bluetooth 5.3/5.4** wireless onboard

Up to 1.8 GHz quad-core Cortex-A53 and **400 MHz Cortex-M4**



Our customers asked for a high performance, robust SoM that simplifies their BOM, has reliable connectivity, uses a standard form factor, and is globally certified. One with multiple software options, a proven security architecture, long term software support, and security fixes.

Our new Nitrogen8M Mini SMARC is powered by **NXP's class-leading i.MX 8M Mini** processor, **NXP PMIC PF8121**, and our Sona WiFi 6/6E and Bluetooth 5.3/5.4 wireless module families based on leading **NXP** and **Infineon** solutions, high performance LPDDR4 RAM, and eMMC storage. We combine this with our common SMARC carrier board; together they can serve as a single board computer (SBC) that can speed your product to market. Alternately, work with us to create a custom carrier that fits your mechanical, environmental, temperature, and interface requirements.

- **Powerful Heterogenous Multiprocessing:** Up to 1.8 GHz quad-core Cortex-A53 microprocessor and 400 MHz Cortex-M4 microcontroller allow you to run Linux and an RTOS on dedicated, hardware-firewalled subsystems.
- **Diversity of Interfaces:** Display, network, data, audio and camera interfaces.
- **SMARC 2.1.1 Standard Form Factor:** 82mm x 50mm SMARC edge connector form factor which includes **onboard ethernet PHY** and a **USB hub controller**. One design supports multiple processor, memory, and wireless configurations.
- **Hardware Upgrade Roadmap:** Build a product design that can easily be upgraded to the latest processors and wireless options as future Laird Connectivity SOMs based on the SMARC standard are released.
- **Advanced Common Carrier/Development Board:** Display, camera, audio, Ethernet, USB, PCI-Express, I2C, SPI, UART, and more. Use in development, as an SBC equivalent in a product, or as reference designs for your carrier board design.

- **Multiple options for Wi-Fi 6/6E (802.11ax) and Bluetooth 5.3/5.4**
 - Sona NX611 (**NXP IW611**) dual-band Wi-Fi 6 and Bluetooth 5.3
 - Sona IF573 (**Infineon CYW55573**) tri-band Wi-Fi 6E and Bluetooth 5.4
- **Operating Temperature Range**
 - Commercial Rating (0° to +70 °C)
 - Industrial Rating (-40° to +85 °C)
- **Multiple high performance memory options:**

1GB LPDDR4 /	2GB LPDDR4 /	4GB LPDDR4 /
16GB eMMC	16GB eMMC	16GB eMMC
- Extensive range of **pre-certified antennas** for optional Sona wireless modules
- **US based manufacturing with Global Options:** Manufacture in USA for local customer base and US market needs. Global manufacturing capability as part of Laird Connectivity footprint, growing reach to EMEA & APAC regions
- **Diverse Software and Board Support Options:** Choose from Yocto Linux/Buildroot Linux/Android/Ubuntu for Cortex-A53s, Zephyr RTOS/FreeRTOS for the Cortex-M7
- **Secure and Encrypted Boot, Secure Enclave, and Secure File Storage:** Robust, secure, and optionally encrypted boot mechanism to ensure only trusted software boots on your device. Optionally store and use secure keys, certificates, and credentials in run-time isolated trusted environment.
- **Power Efficient:** NXP PMIC, power optimized LPDDR4 and eMMC memory, core shut off, clock/voltage scaling, low power interfaces, power optimized single stream Wi-Fi mode enable highly optimized power consumption
- **Long term hardware availability and software support:** Laird Connectivity's products are specifically designed to meet the needs of the industrial and medical markets, which typically require 10 year or more product lifecycles. **Long-term software support** includes LTS Yocto Linux and Zephyr RTOS support with vulnerability remediation.

FEATURES AT A GLANCE



RELIABLE CONNECTIVITY: OPTIONAL WI-FI 6/6E AND BT 5.3/5.4

Excellent Wi-Fi and BT Classic / LE connectivity in difficult environments, plus enterprise Wi-Fi support via WPA3-Enterprise for more secure and robust connections.



GRAPHICS, VIDEO, VISION, AND AUDIO

MIPI-DSI or LVDS display up to 1080p60, GPU, 1080p60 multi codec encode and decode VPU, MIPI-CSI camera interface, I2S audio interfaces



SECURE ENCLAVE AND SECURE BOOT POWERED BY I.MX 8M MINI

Dedicated on-board security hardware, secure boot Linux, and high-performance and flexible secure storage system for passwords, certificates, and data storage.



ROBUST SOFTWARE AND SPEED TO MARKET

Choose from Yocto Linux, Buildroot Linux, Android, and Ubuntu for the Cortex-A53s, Zephyr RTOS and FreeRTOS for the Cortex-M7



GLOBAL RADIO APPROVALS

Sona wireless modules carry several modular FCC, IC, CE, UKCA, RCM, MIC, KC and Bluetooth SIG approvals.



PERSONAL SUPPORT FROM DESIGN TO MANUFACTURE

Our industry-renowned support and field application engineering team is passionate about helping you speed your design to market.

APPLICATION AREAS



Smart Buildings and Appliances



Touchscreens and Displays



Industrial IoT, Vision Systems



Food and Beverage



Medical Devices

KEY SPECIFICATIONS

CATEGORY	FEATURE	SPECIFICATION
Processors	Microprocessor	4x Cortex®-A53 cores @ up to 1.8 GHz
	Microcontroller	1x Cortex®-M4 core @ 400 MHz
	Graphics	GC7000NanoUltra for 3D and GC520L for 2D
Memory	RAM	1GB, 2GB, and 4GB
	Storage	16GB. <i>(For custom sizes, please contact Sales)</i>
Graphics and Video	Graphics Processing Unit	<ul style="list-style-type: none"> ▪ 50 million triangles/sec ▪ 500 megapixel/sec ▪ 8 GFLOPs 32-bit ▪ OpenGL ES 2.0 ▪ 2D acceleration
	Video Processing Unit	<p>Video Decode</p> <ul style="list-style-type: none"> ▪ 1080p60 HEVC/H.265 ▪ 1080p60 VP9 Profile 0, 2 ▪ 1080p60 VP8 ▪ 1080p60 AVC/H.264 Baseline, Main, High decoder <p>Video Encode</p> <ul style="list-style-type: none"> ▪ 1080p60 AVC/H.264 encoder
	Display Interfaces	<ul style="list-style-type: none"> ▪ 1x MIPI DSI, up to 1080p60 ▪ 1x LVDS, up to 1080p60 (Optional, MOQ required)
Vision	Camera	<ul style="list-style-type: none"> ▪ 1x 4-lane MIPI CSI
Audio	Audio Interfaces	<ul style="list-style-type: none"> ▪ 2x I2S (Optionally 1 as HDA) ▪ 1x PCM (for onboard optional Bluetooth)
	Input/Output	<ul style="list-style-type: none"> ▪ 1x PCIe Gen2 1-Lane Dual Mode with PHY ▪ 3x USB 2.0 with PHY ▪ 1x Gbit Ethernet including PHY with IEEE® 1588, AVB, EEE ▪ 3x UART ▪ 5x I2C ▪ 2x SPI ▪ 1x SDIO 3.0/eMMC 5.1 ▪ 14x GPIO
Optional Wireless Specification	Wi-Fi	Wi-Fi 6/6E (802.11ax)
	Frequency	Dual-Band 2.4GHz & 5GHz or Tri-Band 2.4GHz, 5GHz, & 6GHz
	Bluetooth	Bluetooth 5.3/5.4
Supply Voltage		5 V
Physical	Dimensions	SMARC 2.1.1 Standard - 82mm x 50mm
Environmental	Temp Range	0°C to +70°C (Commercial) and -40° to +85 °C (Industrial)
Miscellaneous	Lead Free	Lead-free and RoHS-compliant
	Carrier Board	Carrier board, accessories, and evaluation software
Qualifications	Bluetooth® SIG	Bluetooth SIG Qualified Listing
Regulatory	Approvals	FCC/IC/CE/MIC/RCM on optional Sona wireless modules

For full specifications on the Nitrogen8M Plus SMARC, please see the appropriate datasheet.

Part #	Description
8MM_SMARC_SOM_1r16e	SMARC SOM: i.MX8M MINI Quad / 1GB / 16GB eMMC
8MM_SMARC_SOM_2r16e	SMARC SOM: i.MX8M MINI Quad / 2GB / 16GB eMMC
8MM_SMARC_SOM_4r16e	SMARC SOM: i.MX8M MINI Quad / 4GB / 16GB eMMC
8MM_SMARC_SOM_1r16e_i	SMARC SOM: i.MX8M MINI Quad / 1GB / 16GB eMMC / -40 to +85C
8MM_SMARC_SOM_2r16e_i	SMARC SOM: i.MX8M MINI Quad / 2GB / 16GB eMMC / -40 to +85C
8MM_SMARC_SOM_4r16e_i	SMARC SOM: i.MX8M MINI Quad / 4GB / 16GB eMMC / -40 to +85C
SMARC_CAR_BRD	Universal Carrier Board - SMARC (Note - SOM sold separately)

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